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(54) METHOD AND APPARATUS FOR HEAT SINK MOUNTING

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(57)**ABSTRACT**

A method is disclosed of mounting a heat sink through a printed circuit board to reach a component on the opposite side of a board. The heat sink is passed through a window in the board to contact a component at a predetermined pressure optimized for thermal performance at minimum stress. The heat sink is affixed in place on the printed circuit board using through-hole pins which can be soldered to maintain the heat sink's position and the predetermined pressure.

